## IN THE CLAIM

Please cancel Claims 1 to 9, without prejudice or disclaimer of the subject matter thereof, and add new claims 10 to 15. The added new claim 10 is the incorporation of the original claims 2, 3 and 4. The added new claim 11 adds the features in the original claim 5 to the new claim 10. The added new claim 12 adds the features in the original claim 6 to the new claim 10. The added new claim 13 adds the features in the original claim 7 to the new claim 10. The added new claim 14 adds the features in the original claim 8 to the new claim 10. The added new claim 10. The relations of the new claim with respect to the original claims are shown in the following Remark by which Examiner can understand the structure of new claims with respect to the original claims clearly.

## LIST OF CLAIMS:

Claim 10. (New claim) A semiconductor waste-gas treating apparatus having the ability of preventing sedimentation and etching of filth, wherein said apparatus comprises a header, a waste gas treating trough and an annular guide in which said waste gas treating trough is mounted below said header and has at the center thereof a reaction room, said apparatus is characterized by:

said reaction room is surrounded by a water receiving chamber outside of it, said water receiving chamber is provided on the top thereof with an annular spillway in communicating with said reaction room; and said annular guide is mounted at said annular spillway, by guiding of said annular guide, water is smoothly and uniformly distributed to said annular spillway, and spills to said reaction room to form an annular water wall on the wall of said reaction room; and

wherein, said water receiving chamber is provided with a water

inlet and a water discharge outlet; and

wherein, a sensing probe is provided in said annular spillway to detect whether there is water entering said water receiving chamber.

Claim 11. (New claim) A semiconductor waste-gas treating apparatus having the ability of preventing sedimentation and etching of filth as claimed in claim 10, wherein, said header is provided with a sensing probe used to sense the reaction temperature in a reaction room.

Claim 12. (New claim) A semiconductor waste-gas treating apparatus having the ability of preventing sedimentation and etching of filth as claimed in claim 11, wherein, said sensing probe is provided therearound with a plurality of hydrogen spraying nozzles and a plurality of waste gas delivery pipes for delivering hydrogen and semiconductor waste gas.

Claim 13. (New claim) A semiconductor waste-gas treating apparatus having the ability of preventing sedimentation and etching of filth as claimed in claim 12, wherein, said hydrogen spraying nozzles are provided each with a fire spraying port on the front end thereof.

Claim 14. (New claim) A semiconductor waste-gas treating apparatus having the ability of preventing sedimentation and etching of filth as claimed in claim 10, wherein, said annular spillway is provided with no sensing probe.

Claim 15. (New claim) A semiconductor waste gas treating apparatus having the ability of preventing sedimentation and etching of filth as claimed in claim 10, wherein, said annular guide is provided on the top thereof with an annular flange.